



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-10-29
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Flavio Di Francesco	<b>Representative Title</b>	AMS Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FB6R*VA18AAAY	A	ZY1A	2015-10-29
Amount	UoM	Unit type	ST ECOPACK Grade	
54.82	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
DSO	5-4.4-0.9	14	gull wing
Comment	Package: 6R TSSOP 14 BODY 4.4 PITCH 0.65; MD valid for TSZ124IYPT		

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	FB6R*VA18AAY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.812	mg	supplier	die	Silicon (Si)	7440-21-3		0.748	mg	921182	13645
Die			mg	supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	11084	164
Die			mg	supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	2463	36
Die			mg	supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1232	18
Die			mg	supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	3695	55
Die			mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.018	mg	22167	328
Die			mg	supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.018	mg	22167	328
Die			mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.013	mg	16010	237
Leadframe	Copper and its alloy	31.124	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.192	mg	937926	532506
Leadframe			mg	supplier	alloy	Iron (Fe)	7439-89-6		0.703	mg	22587	12824
Leadframe			mg	supplier	alloy	Zinc (Zn)	7440-66-6		0.035	mg	1125	638
Leadframe			mg	supplier	alloy	Iron Phosphide (Fe2P)	7723-14-0		0.009	mg	289	164
Leadframe			mg	supplier	metallization	Silver(Ag)	7440-22-4		1.185	mg	38074	21616
Die attach	Other organic materials	0.378	mg	supplier	glue	Silver (Ag)	7440-22-4		0.304	mg	804233	5545
Die attach			mg	supplier	glue	Bisphenol F type epoxy resin	9003-36-5		0.03	mg	79365	547
Die attach			mg	supplier	glue	Epoxy resin	68475-94-5		0.011	mg	29101	201
Die attach			mg	supplier	glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.011	mg	29101	201
Die attach			mg	supplier	glue	Gamma Butyrolactone	96-48-0		0.011	mg	29101	201
Die attach			mg	supplier	glue	Polyoxypropylenediamine	9046-10-0		0.011	mg	29101	201
Bonding wire	Precious metals	0.3	mg	supplier	wire	Gold (Au)	7440-57-5		0.3	mg	1000000	5472
Encapsulation	Other inorganic materials	20.823	mg	supplier	molding compound	Epoxy resin	Proprietary		2.082	mg	99986	37979
Encapsulation			mg	supplier	molding compound	Phenol resin	Proprietary		1.04	mg	49945	18971
Encapsulation			mg	supplier	molding compound	Silica, vitreous	60676-86-0		17.596	mg	845027	320978
Encapsulation			mg	supplier	molding compound	Carbon black	1333-86-4		0.105	mg	5043	1915
Finishing	Other inorganic materials	1.383	mg	supplier	external plating	Tin (Sn)	7440-31-5		1.383	mg	1000000	25228